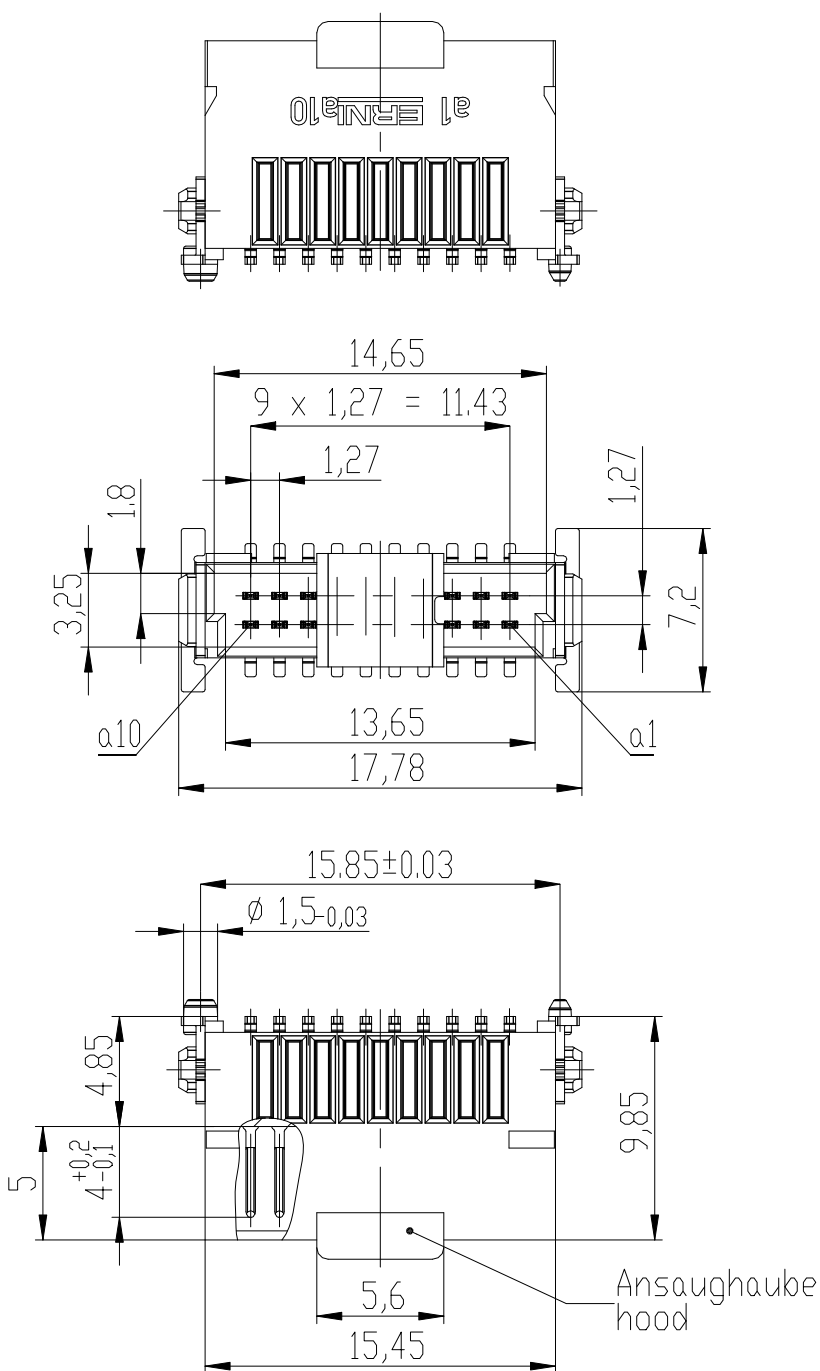
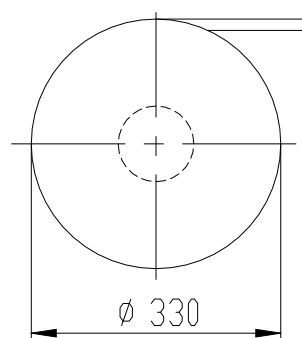


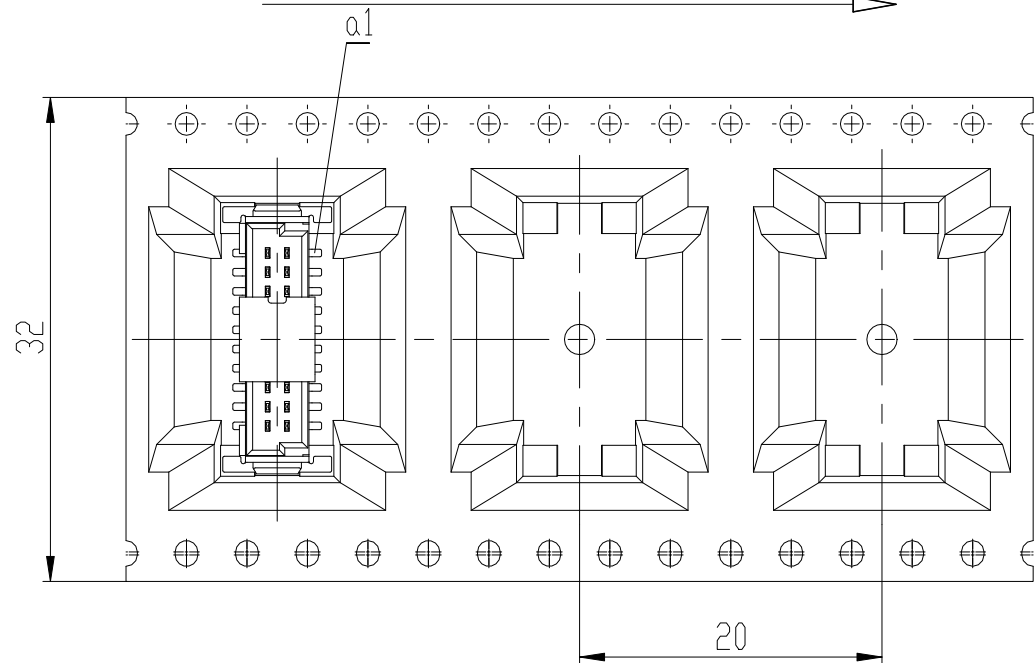


Anforderungsstufe 1
performance level 1
Kontaktbereich vergoldet
mating area gold plating
Anschlussbereich verzinkt 4-6 µm
terminal area 4-6 µm tin plating
Koplanarität der Anschlüsse ≤ 0,1 mm
coplanarity area of termination ≤ 0,1 mm

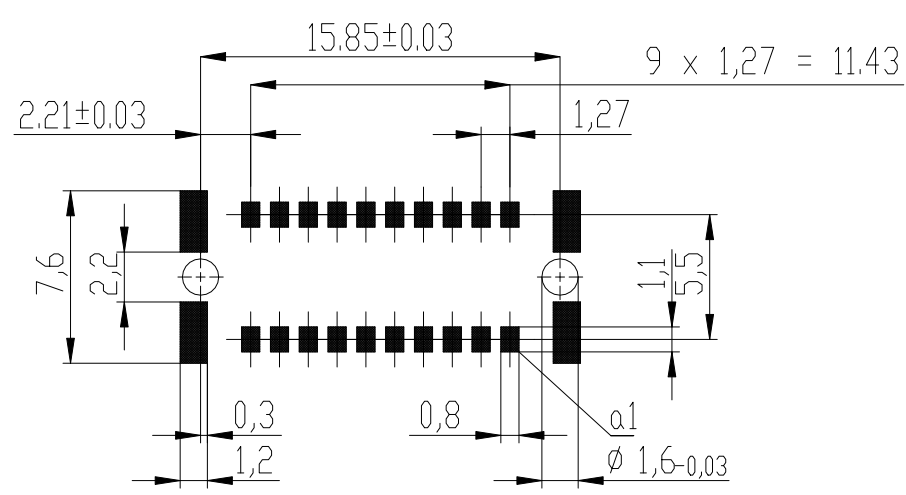
Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 250 Stück
packaging unit: 250 pcs



Abspulrichtung - Reel off Direction

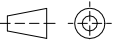


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



BA 8-23 - hohe Bauhöhe
type 8-23 - High Profile

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Information:				Tolerances		 All Dimensions in mm		Scale 3:1			
<u>Customer drawing:</u> THIS DRAWING IS A CONTROLLED DOCUMENT.				Subject to modification without prior notice. Drawing will not be updated.		Designation ERNI-Messerl. SMC-Q 20-SMD-BA8-23 Male SMC-Q 20-SMD-type8-23					
						 TE Connectivity					
f		06.11.2018		 TE Connectivity		C- 254415-E				I	
Index		Date				Class SMCQ				A3	

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